



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPG20N04S4-12A	<b>Issued</b>	13. May 2021
<b>MA#</b>	MA002193038		
<b>Package</b>	PG-TDSON-8-10	<b>Weight*</b>	99.11 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.868	0.88	0.88	8760	8760
chip_2	inorganic material	silicon	7440-21-3	0.868	0.88	0.88	8760	8760
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		132	
	non noble metal	iron	7439-89-6	0.044	0.04		441	
	non noble metal	copper	7440-50-8	43.681	44.07	44.12	440722	441295
wire	non noble metal	aluminium	7429-90-5	0.799	0.81	0.81	8056	8056
encapsulation	organic material	carbon black	1333-86-4	0.092	0.09		925	
	plastics	epoxy resin	-	6.512	6.57		65698	
	inorganic material	silicondioxide	60676-86-0	39.253	39.60	46.26	396036	462659
leadfinish	non noble metal	tin	7440-31-5	1.396	1.41	1.41	14089	14089
plating	inorganic material	phosphorus	7723-14-0	0.001			15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6085	6100
solder	non noble metal	tin	7440-31-5	0.046	0.05		460	
	noble metal	silver	7440-22-4	0.057	0.06		575	
	non noble metal	lead	7439-92-1	2.179	2.20	2.31	21981	23016
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			27	
	non noble metal	copper	7440-50-8	2.699	2.72	2.72	27230	27265
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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